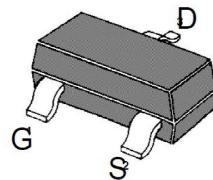
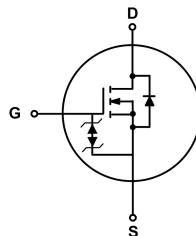


## N-Channel Enhancement Mode MOSFET

**Features**RDS(ON)  $\leqslant$  2.3  $\Omega$  @ VGS=10VRDS(ON)  $\leqslant$  2.7  $\Omega$  @ VGS=4.5V**SOT-23****Applications**

Portable appliances

**N-CHANNEL MOSFET****Maximum ratings ( $T_a=25^\circ\text{C}$  unless otherwise noted)**

Symbol	Parameter	Conditions	Min	Max	Unit
$V_{DS}$	Drain-Source Voltage	$T_A = 25^\circ\text{C}$	-	60	V
$V_{GS}$	Gate-Source Voltage	$T_A = 25^\circ\text{C}$	-	$\pm 20$	V
$I_D^*$	Drain Current	$T_A = 25^\circ\text{C}, V_{GS} = 10\text{ V}$	-	0.5	A
$I_{DM}^{*,**}$	Pulsed Drain Current	$T_A = 25^\circ\text{C}, V_{GS} = 10\text{ V}$	-	2.0	A
$P_{tot}^*$	Total Power Dissipation	$T_A = 25^\circ\text{C}$	-	0.83	W
		$T_A = 100^\circ\text{C}$	-	0.33	
$T_{stg}$	Storage Temperature		-55	150	$^\circ\text{C}$
$T_J$	Junction Temperature		-	150	$^\circ\text{C}$
$I_S^*$	Diode Forward Current	$T_A = 25^\circ\text{C}$	-	0.5	A
$R_{\theta JA}^*$	Thermal Resistance- Junction to Ambient		-	150	$^\circ\text{C} / \text{W}$

Notes :

\* Surface Mounted on 1 in<sup>2</sup> pad area, t  $\leq$  10 sec\*\* Pulse width  $\leq$  300  $\mu\text{s}$ , duty cycle  $\leq$  2 %

**Electrical Characteristics ( TA = 25 °C Unless Otherwise Noted )**

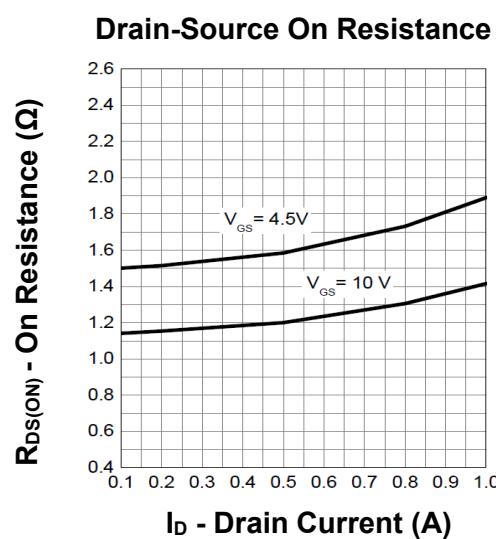
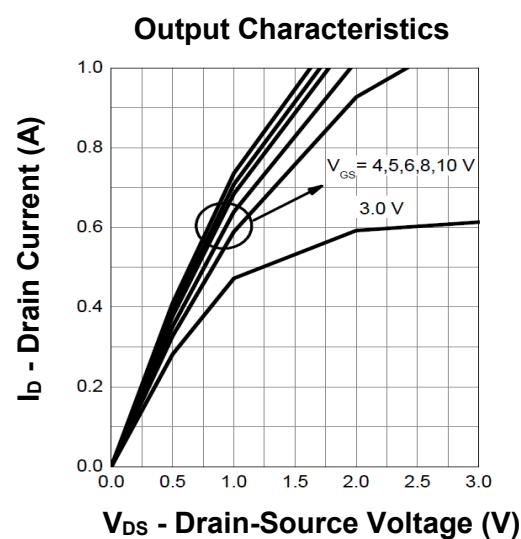
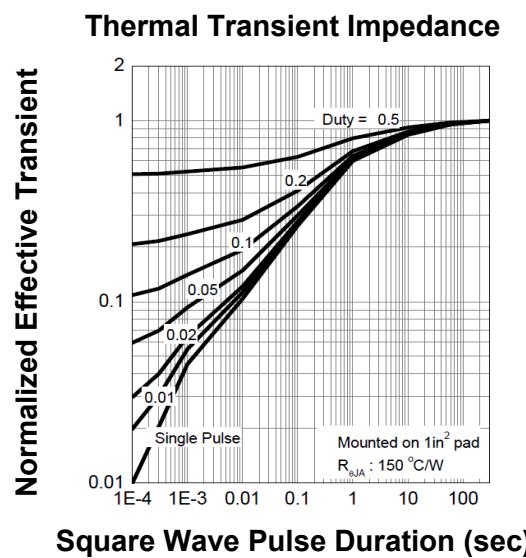
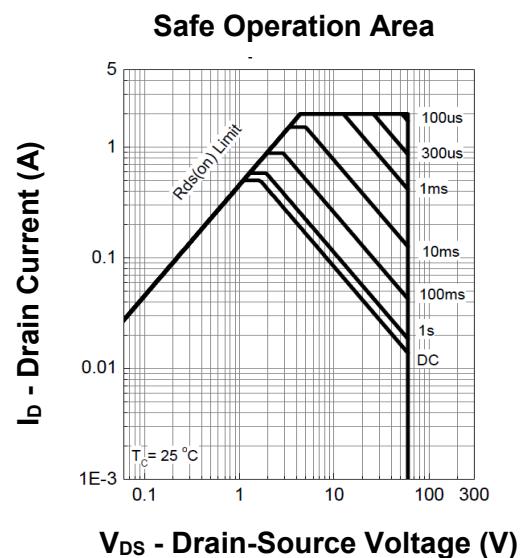
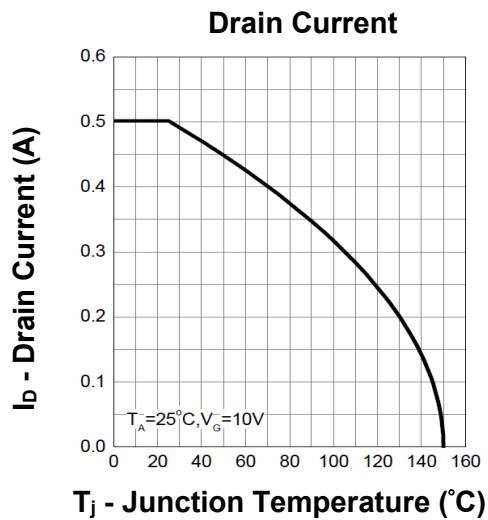
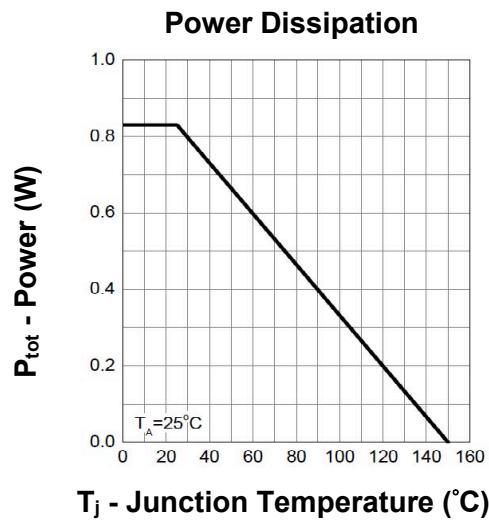
Symbol	Parameter	Conditions	Min	Typ	Max	Unit
<b>Static Characteristics</b>						
BV <sub>DSS</sub>	Drain-Source Breakdown Voltage	V <sub>GS</sub> = 0 V, I <sub>DS</sub> = 250 µA	60	-	-	V
V <sub>GS(th)</sub>	Gate Threshold Voltage	V <sub>DS</sub> = V <sub>GS</sub> , I <sub>DS</sub> = 250 µA	0.5	-	1.5	V
I <sub>DSS</sub>	Drain Leakage Current	V <sub>DS</sub> = 48 V, V <sub>GS</sub> = 0 V T <sub>J</sub> = 85 °C	-	-	1	µA
I <sub>GSS</sub>	Gate Leakage Current	V <sub>GS</sub> = ± 20 V, V <sub>DS</sub> = 0 V	-	-	± 10	µA
R <sub>DSON</sub> <sup>a</sup>	On-State Resistance	V <sub>GS</sub> = 10 V, I <sub>DS</sub> = 0.5 A	-	-	1.6	Ω
		V <sub>GS</sub> = 4.5 V, I <sub>DS</sub> = 0.1 A	-	-	2.5	
<b>Diode Characteristics</b>						
V <sub>SD</sub> <sup>a</sup>	Diode Forward Voltage	I <sub>SD</sub> = 0.5 A, V <sub>GS</sub> = 0 V	-	-	1.3	V
t <sub>rr</sub>	Reverse Recovery Time	I <sub>SD</sub> = 0.5 A, dI <sub>SD</sub> / dt = 100 A / µs	-	42	-	ns
Q <sub>rr</sub>	Reverse Recovery Charge		-	41	-	nC
<b>Dynamic Characteristics<sup>b</sup></b>						
R <sub>G</sub>	Gate Resistance	V <sub>GS</sub> = V <sub>DS</sub> = 0 V, F = 1 MHz	-	100	-	Ω
C <sub>iss</sub>	Input Capacitance	V <sub>GS</sub> = 0 V, V <sub>DS</sub> = 25 V Frequency = 1 MHz	-	22.8	-	pF
C <sub>oss</sub>	Output Capacitance		-	3.5	-	
C <sub>rss</sub>	Reverse Transfer Capacitance		-	2.9	-	
t <sub>d(on)</sub>	Turn-on Delay Time	V <sub>DS</sub> = 30 V, V <sub>GEN</sub> = 10 V, R <sub>G</sub> = 25 Ω, R <sub>L</sub> = 60 Ω, I <sub>DS</sub> = 0.5 A	-	3.8	-	ns
t <sub>r</sub>	Turn-on Rise Time		-	3.4	-	
t <sub>d(off)</sub>	Turn-off Delay Time		-	19	-	
t <sub>f</sub>	Turn-off Fall Time		-	12	-	
Q <sub>g</sub>	Total Gate Charge	V <sub>GS</sub> = 4.5 V, V <sub>DS</sub> = 10 V, I <sub>DS</sub> = 0.5 A	-	280	-	pC
Q <sub>gs</sub>	Gate-Source Charge		-	82	-	
Q <sub>gd</sub>	Gate-Drain Charge		-	201	-	

Notes :

a : Pulse test ; pulse width ≤ 300 µs, duty cycle ≤ 2 %

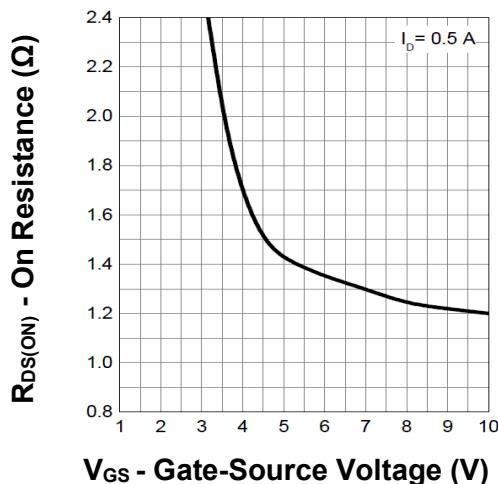
b : Guaranteed by design, not subject to production testing

### Typical Characteristics

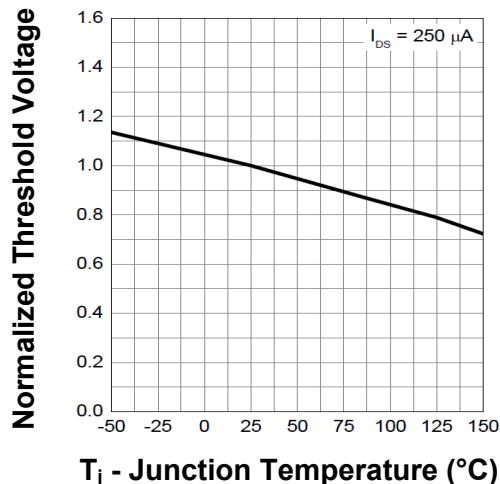


## Typical Characteristics (cont.)

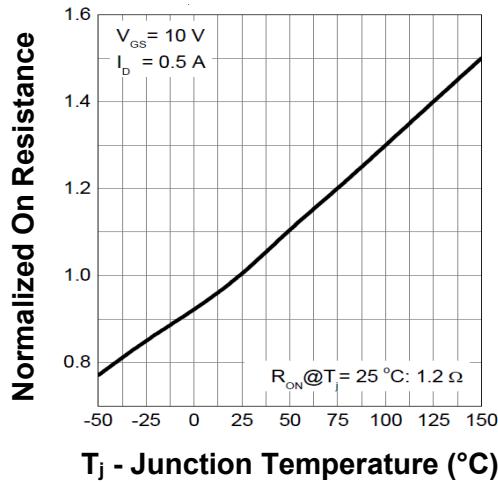
Transfer Characteristics



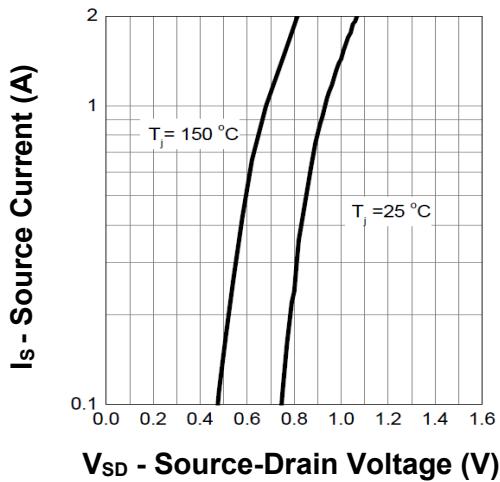
Gate Threshold Voltage



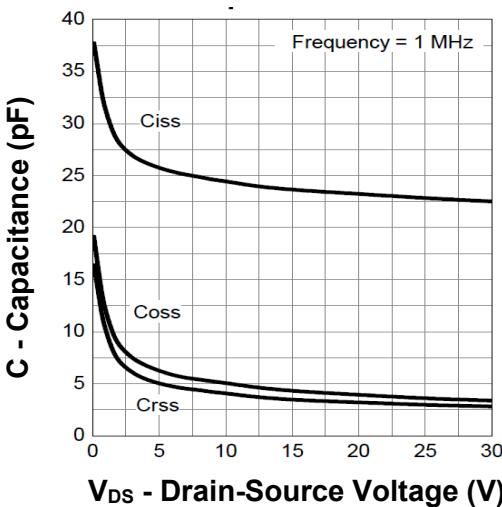
Drain-Source On Resistance



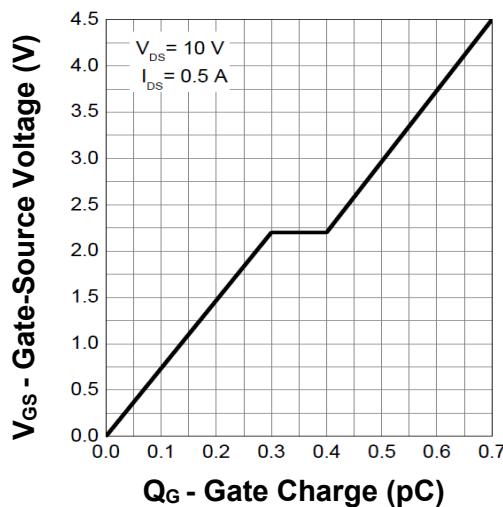
Source-Drain Diode Forward



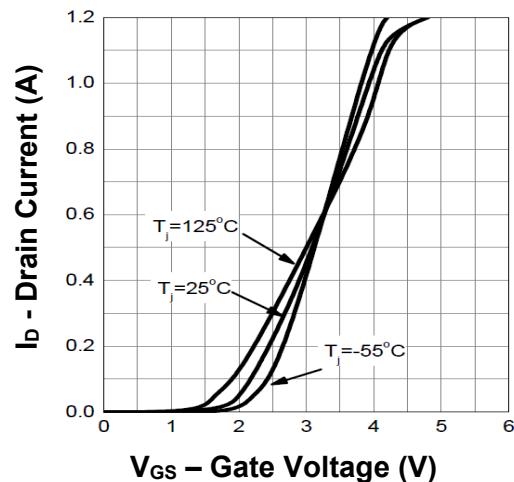
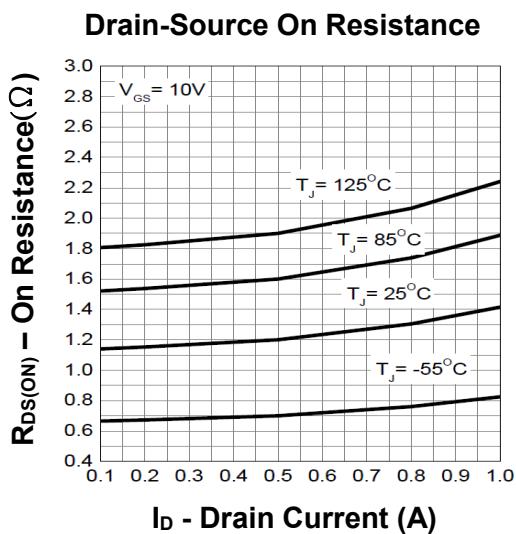
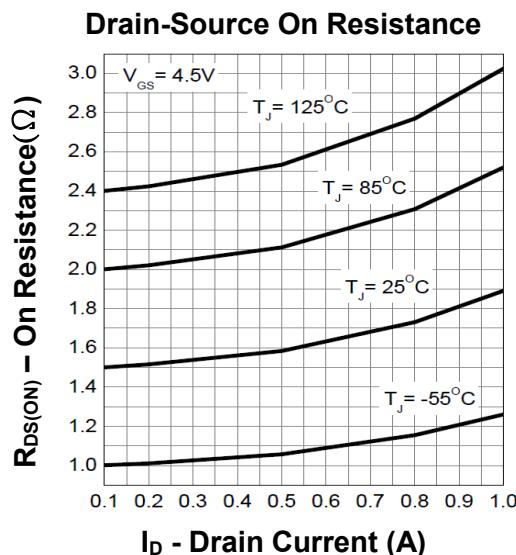
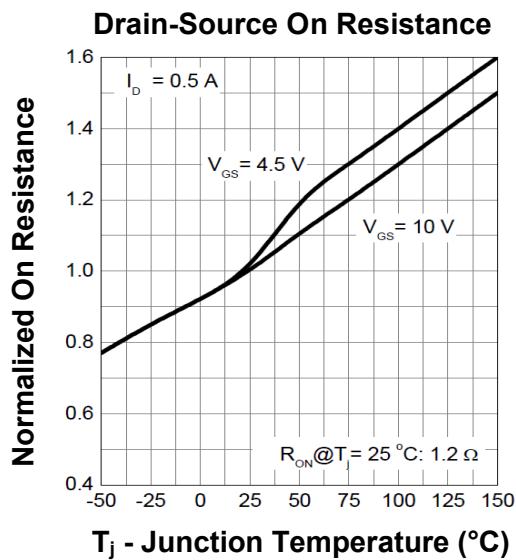
Capacitance

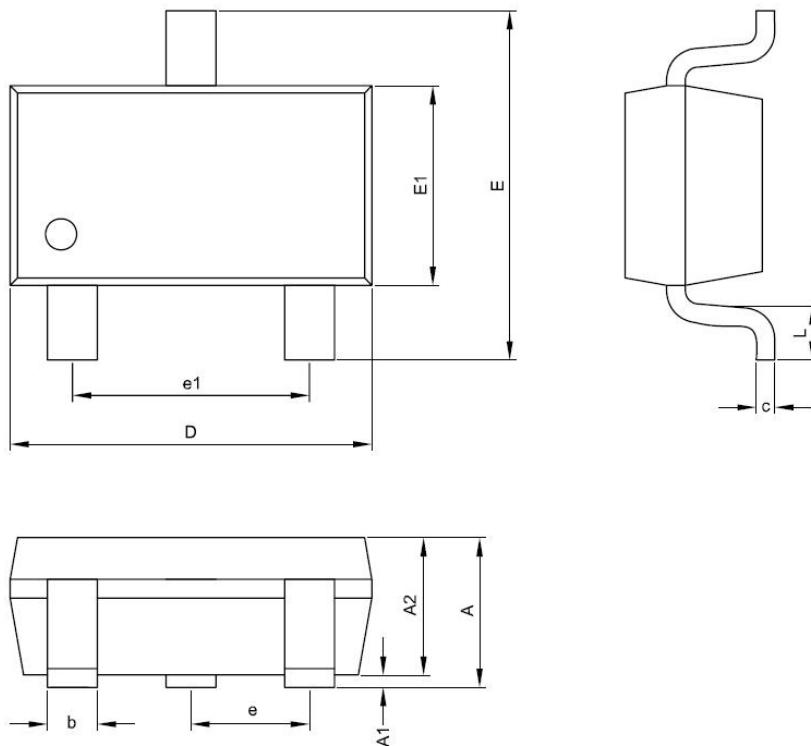


Gate Charge



## Typical Characteristics (cont.)



**SOT-23 Package Dimensions**

Symbol	MIN.	MAX.
A	—	1.12
A1	0.00	0.1
A2	0.90	1.02
D	2.90 BSC	
E	2.40 BSC	
E1	1.20	1.40
c	0.08	0.25
b	0.30	0.50
e	0.95 BSC	
e1	1.90 BSC	
L	0.20	0.60

Unit: mm